

WHAT IS CLAIMED IS:

1. A processing method for a device wafer in which a front surface of the device wafer on which a device is formed in each of chip regions partitioned by a plurality of scheduled division lines formed in a crossing relationship on the front surface of the device wafer is sealed with a sealing member and a plurality of bumps are formed individually in the chip regions of the sealing member, the processing method comprising:

an alignment step of detecting alignment marks of the device wafer through the sealing member from the surface side of the device wafer by visible light image pickup means and detecting a scheduled division line to be cut based on the alignment marks; and

a division step of cutting, after the alignment step is carried out, the device wafer along the scheduled division line from the surface side of the device wafer by a cutting blade to divide the device wafer into individual device chips sealed at the surface thereof with the sealing member; wherein

the alignment step is carried out while light is irradiated in an oblique direction upon a region, whose image is to be picked up by the visible light image pickup means, by oblique light means,

the sealing member contains carbon black,
the content of the carbon black is 0.1% by mass or
more and 0.2% by mass or less, and

in the alignment step, the vertical illumination of
visible light image pickup means and the light from
oblique illumination means are applied to the region to
be imaged by visible light image pickup means.